

# LS 2000 – Coater and Developer Systems



## Modular, flexible, expandable – one platform, many solutions

LS Series are fully automated Coater- and Developer Systems. Different, individually chosen processing modules and carriers for various substrate types and sizes may be combined on one of our three basis platforms (LS1000, LS2000, LS2500) - utmost flexibility for sophisticated applications.

### System Features

- Flexible tool configuration with up to 8 processing modules and 4 I/O stations
- Wafer sizes up to 200mm diameter
- Standard- and Thin-wafer processing
- Small footprint (1.4 m<sup>2</sup>, 2.4m<sup>2</sup> or 2.8m<sup>2</sup>)
- High throughput
- User friendly software
- SECS/GEM interface
- Customer specific solutions

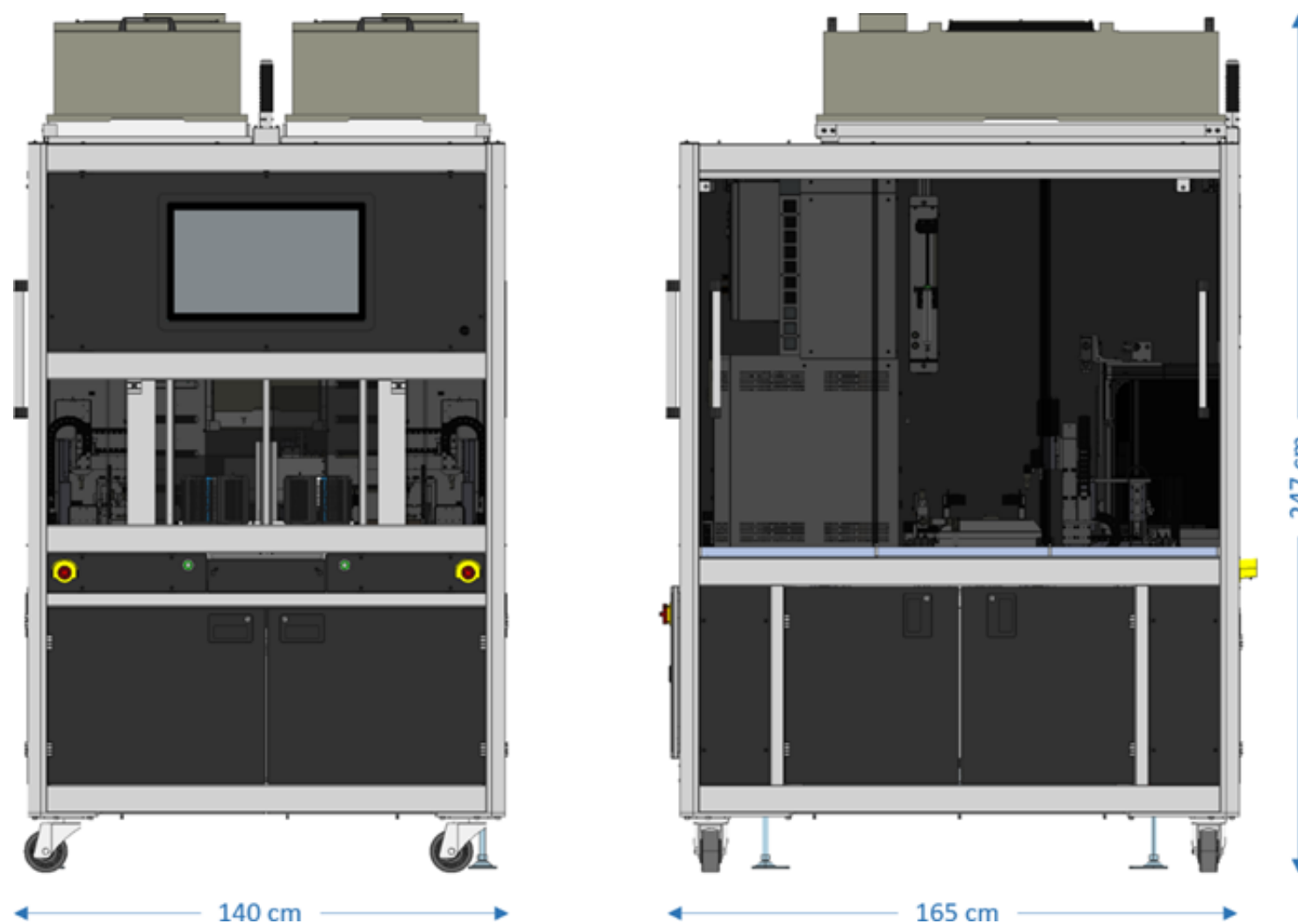
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## Handling System

- 3-axis Pick & place robot
- Contactless wafer centering "on-the-fly"
- OCR, bar and matrix code support
- Edge gripping of wafers available
- Intelligent cassette slot scanning detects carrier type, wafer size and double or cross loaded slots



## Developer Module

- Proven process bowl design with symmetric exhaust
- Dispense system for up to 3 different developer media per bowl
- Various developer media can be applied by:
  - » Puddle nozzle
  - » Fan spray nozzle
  - » Binary spray nozzle
- Programmable top-, backside & bowl rinse



## Coater Module

- Optimized bowl design with symmetric exhaust for optimal process results
- Programmable Edge Bead Removal, wafer backside and bowl rinse
- Dispense system for up to 5 different media per bowl with automatic nozzle change
- Range of resist pumps to choose from:
  - » Customer-specific
  - » Pressure tank
  - » Stepper motor driven pump
  - » Syringe
- Spin- and spray coating



## Hot- and Coolplate Module

- Up to 5 hot- or coolplates per module
- Standard hotplate (60°C - 200°C)
- High-temperature hotplate (60°C - 450°C)
- Hotplate with heated cover
- HMDS Primer hotplate (60°C - 200°C)
- Coolplates (15°C - 45°C), with either water or Peltier cooling
- Distance control via
  - » Programmable proximity
  - » Fixed proximity
  - » Vacuum contact